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Dimensions

Chip Size	0603
L	1.6mm +0.2/-0.15mm (0.063 in +0.008/-0.006 in)
W	0.81mm +0.2/-0.15mm (0.032 in +0.008/-0.006 in)
T	1.02mm MAX (0.04 in MAX)
B	0.41mm +/-0.2mm (0.016 in +/-0.008 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	368

General Information

Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov
Termination	Solder Plated
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	2.7 pF
Capacitance Tolerance	+/-0.1 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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